Material Declaration Report

Package Type:	BQSOP 48L
Pericom Package Code:	B48(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	160.6670
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10~20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	30
Reflow Cycles:	3
Rev Date:	11/5/2009

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
			Silica Fused	60676-86-0	90.800	91.9905
MOLD COMPOUND	101.3111	OSE	Epoxy Resin 1	Proprietary	3.000	3.0393
			Phenolic Resin	Proprietary	3.000	3.0393
			Epoxy Resin 2	Proprietary	2.000	2.0262
			Aromatic Phosphate	Proprietary	1.000	1.0131
			Carbon Black	1333-86-4	0.200	0.2026
			Silica Fused	60676-86-0	88.000	89.1538
		SPEL	Epoxy Resin	Proprietary	5.000	5.0656
			Phenolic Resin	Proprietary	4.500	4.5590
			Epoxy, Cresol Novolac	29690-82-2	2.000	2.0262
			Carbon Black	1333-86-4	0.500	0.5066
			Copper	7440-50-8	97.021	49.8936
LEADFRAME	51.4257		Iron	7439-89-6	2.350	1.2085
			Silver	7440-22-4	0.453	0.2331
			Zinc	7440-66-6	0.111	0.0570
			Phosphorus	7723-14-0	0.065	0.0334
SILICON DIE	2.7637		Silicon (Si)	7440-21-3	99.192	2.7414
			Non-hazardous Metal	Proprietary	0.808	0.0223
			Silver	7440-22-4	76.000	0.1977
DIE ATTACH EPOXY	0.2601	OSE	Acrylic Resin	Proprietary	8.000	0.0208
			Acrylate	Proprietary	5.500	0.0143
			Polybutadiene derivative	Proprietary	5.500	0.0143
			Epoxy resin	Proprietary	2.500	0.0065
			Additive	Proprietary	1.000	0.0026
			Butadiene copolymer	Proprietary	1.000	0.0026
			Peroxide	Proprietary	0.500	0.0013
			Silver	7440-22-4	80.000	0.2081
		SPEL	Epoxy Resin	9003-36-5	10.000	0.0260
			Diluent	26447-14-3	6.000	0.0156
			Hardener	620-92-8	3.250	0.0085
			Dicyandamide	461-58-5	0.750	0.0020
GOLD WIRE	0.7432		Gold(Au)	7440-57-5	99.990	0.7431
			Impurities	-	0.010	0.0001
SOLDER PLATING	4.1631		Tin (Sn)	7440-31-5	99.990	4.1627
			Impurity	-	0.010	0.0004

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

	MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
	Mold Compound	<2	<2	<2	<2	<5	<5
	Leadframe	<50	<2	<2	<2	<5	<5
Device	Silicon Die	<2	<2	<2	<2	<5	<5
	Die Attach Epoxy	<2	<2	<2	<2	<5	<5
	Gold Wire	<2	<2	<2	<2	<5	<5
	Solder Plating	<50	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC

and

China RoHS Directive SJ/T11363-2006

Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium

Pb <1000ppm	Hg <1000ppm	Cr+6 <1000ppm	Cd <100ppm	PBB <1000ppm	PBDE <1000ppm
O	O	O	O	O	O

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.